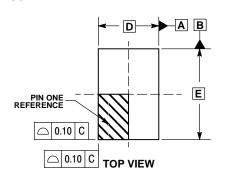
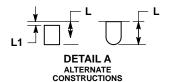
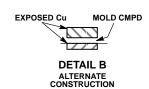


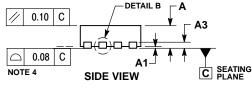
TDFN8, 2x3, 0.5P CASE 511AK **ISSUE B**

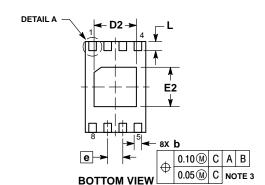
DATE 18 MAR 2015











- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.

 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
Α	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.30	1.50
Е	3.00 BSC	
E2	1.20	1.40
е	0.50 BSC	
L	0.20	0.40
1.1		0.15

GENERIC MARKING DIAGRAM*



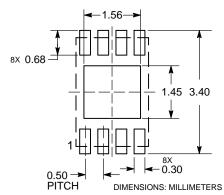
XXXXX = Specific Device Code = Assembly Location

= Wafer Lot WL Υ = Year

W = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " •", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	TDFN8, 2X3, 0.5P	PAGE 1 OF 2	



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ISSUE	REVISION	DATE		
0	RELEASED FOR PRODUCTION FROM POD #TDFN8-008-01 TO ON SEMICONDUCTOR. REQ. BY B. BERGMAN.	19 DEC 2008		
Α	CHANGED DESCRIPTION FROM WDFN TO TDFN.	18 MAR 2009		
В	REDREW PACKAGE DRAWING TO ON SEMICONDUCTOR/JEDEC STANDARD. REQ. BY B. BECKER.	18 MAR 2015		

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